



TSC is an employee owned, high technology, small business engaged in providing engineering services to the U.S. Government and Industry. TSC's Systems Development and Production Division provides products and services in the areas of radar, communication systems, sensors, antennas and other electronics systems to the missile, radar/sensor system, communications, control systems, data acquisition, and signal processing markets. The company has developed products ranging from chip-level, application-specific, integrated circuits (ASIC) to complete, turnkey radar and communication systems. TSC has established a state-of-the-art hardware capability that is well respected by customers in Government and industry. TSC also provides full spectrum systems engineering support including theoretical analysis, requirements generation, interface control, and test planning/execution/data analysis.

The Physical Design Services Group at TSC's Systems Development and Production Division in Huntsville, AL is currently looking to hire a Mechanical Engineer with an education and industry focus in the mechanical/thermal design and packaging of electronics systems such as high density airborne or ruggedized electronics assemblies in support of radars/sensors, missile seekers and communications systems.

Position Description: Mechanical Engineer

Applicants must have a B.S. in Mechanical Engineering from an accredited University and 0-5 years of commensurate industry experience in analysis, design, and layout of electronics hardware components and/or systems. Experience with military electronics packaging including RF, microwave, analog or digital assemblies and subassemblies is desired. Candidate should be capable of weighing product design for manufacturability and cost attributes against product form-fit-function and thermal attributes to achieve the best mix for each unique product and customer requirement. Skill sets should include proficiency with SolidWorks, Solid Edge, Pro-E, or other 3D modeling software with SolidWorks as the preferred tool. A working knowledge of CFD thermal analysis software packages and FEA structural analysis software is a plus. Experience with the following areas is required:

- Experience conducting CFD, Dynamic, Static, and Thermal FEA.
- Basic understanding of machining and electronic system manufacturing processes
- Experience with design for manufacturability.
- Understanding of dimensioning and tolerance
- Ability to read and generate mechanical drawings.
- Experience in 2D and 3D modeling.
- Experience working in a design team environment with vendors, customers and peer engineers.



Experience in any or all of the following areas is beneficial:

- Experienced in the following software packages: Solidworks, Solidworks Simulation Premium, Autodesk Simulation CFD.
- Application of Geometric Dimensioning and Tolerancing (GD&T).
- Experience in microelectronics packing.
- Basic understanding of RF, microwave, analog and digital electronics packaging principles.
- Knowledge of military finishes.
- Experience in a multi-tasking environment and managing daily schedules and tasks to ensure overall program schedule and objectives are met.

Applicant shall have experience developing and presenting concepts and possible solutions to technical problems. Ideal candidate will possess excellent organizational skills with the ability to prioritize work and maximize productivity. Candidate will be a self-motivated and free-thinking individual capable of technical discussion, complex problem solving and scrutinizing prior assumptions.

Applicants must be U.S. citizens and will be required to obtain a security clearance.

TSC is an Equal Opportunity Employer. Qualified Veterans and Protected Class Candidates are encouraged to apply.

Send resumes to:
employment-hsv@tsc.com

Complete application at:
<http://tscphaseiv.iapplicants.com>